

國立交通大學

電子工程學系 電子研究所碩士班

碩士論文

附著力強度與異質接合於三維積體電路應用之
研究



Investigation of Adhesion Strength and Hetero-Bonding
for 3D IC Applications

研究生：黃文君

指導教授：陳冠能 博士

中華民國一〇二年三月

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